

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial Number: 10/681,747  
 Filing Date: October 8, 2003  
 Name of Inventor(s): Marcos Karnezos  
 Title of Invention: SEMICONDUCTOR MULTI-PACKAGE MODULE HAVING INVERTED SECOND PACKAGE STACKED OVER DIE-UP FLIP-CHIP BALL GRID ARRAY (BGA) PACKAGE

**TRANSMITTAL AND REQUEST TO CHANGE**  
**POWER OF ATTORNEY TO PROSECUTE APPLICATIONS BEFORE THE USPTO,**  
**CORRESPONDENCE ADDRESS, AND ATTORNEY DOCKET NO.**

Commissioner for Patents  
 P.O. Box 1450  
 Alexandria, VA 22313-1450

Dear Sir or Madam:

The Assignee of Record is the owner of the entire interest and respectfully requests:

1. Revocation of all previous Powers of Attorney and the appointment of Mikio Ishimaru and all practitioners associated with Customer No. 22898.
2. Change of the correspondence address for the above-identified U.S. Patent Application No. 10/681,747 to the address associated with Customer No. 22898.
3. Change of the Attorney Docket No. from CPAC 1029-6 to 27-409-5CP.

Enclosed are the following documents:

Power Of Attorney To Prosecute Applications Before The USPTO and Change of Correspondence Address

Statement Under 37 CFR 3.73(b)

Fee Address Indication Form PTO/SB/47

Please charge any shortage in fees due in connection with the filing of this paper to Deposit Account 50-0374 and credit any excess fees to such Deposit Account.

Respectfully submitted,

*Mikio Ishimaru*  
 Mikio Ishimaru  
 Reg. No. 27,449  
 January 18, 2008

Certificate of Transmission

I hereby certify that these documents are being electronically transmitted to the U.S. Patent and Trademark Office via EFS from the Pacific Time zone on January 18, 2008

*Victoria Rocha*  
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